LM5104 High-Voltage Half-Bridge Gate Driver With Adaptive Delay

1 Features

- Drives Both a High-Side and Low-Side N-Channel MOSFET
- Adaptive Rising and Falling Edges With Programmable Additional Delay
- Single Input Control
- Bootstrap Supply Voltage Range up to 118-V DC
- Fast Turnoff Propagation Delay (25 ns Typical)
- Drives 1000-pF Loads With 15-ns Rise and Fall Times
- Supply Rail Undervoltage Lockout
- SOIC and WSON-10 4-mm × 4-mm Package

2 Applications

- Current Fed Push-Pull Power Converters
- High Voltage Buck Regulators
- Active Clamp Forward Power Converters
- Half-Bridge and Full-Bridge Converters

3 Description

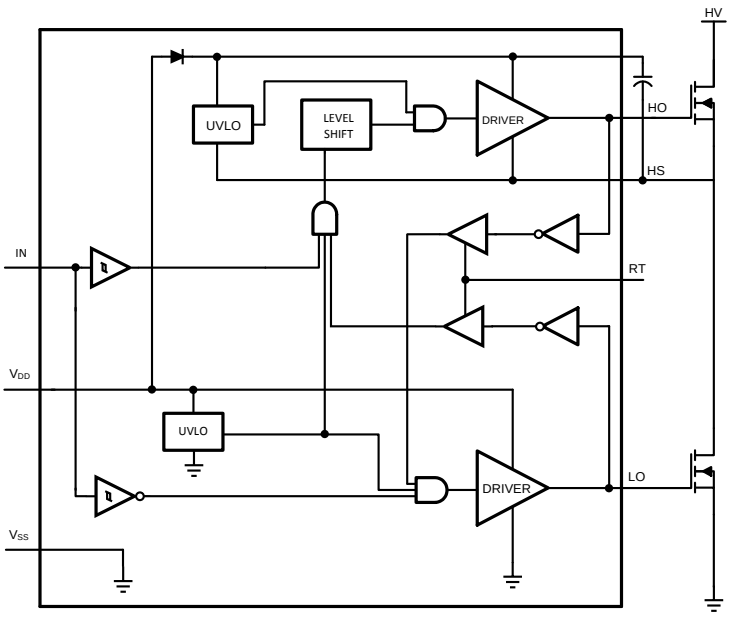
The LM5104 High-Voltage Gate Driver is designed to drive both the high-side and the low-side N-channel MOSFETs in a synchronous buck configuration. The floating high-side driver can work with supply voltages up to 100 V. The high-side and low-side gate drivers are controlled from a single input. Each change in state is controlled in an adaptive manner to prevent shoot-through issues. In addition to the adaptive transition timing, an additional delay time can be added, proportional to an external setting resistor. An integrated high-voltage diode is provided to charge high-side gate drive bootstrap capacitor. A robust level shifter operates at high speed while consuming low power and providing clean level transitions from the control logic to the high-side gate driver. Undervoltage lockout is provided on both the low-side and the high-side power rails. This device is available in the standard SOIC and the WSON packages.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM5104	SOIC (8)	4.90 mm × 3.91 mm
	WSON (10)	4.00 mm × 4.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Simplified Block Diagram



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (March 2013) to Revision D **Page**

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ... 1

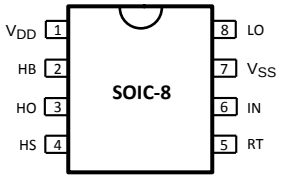
Changes from Revision B (March 2013) to Revision C **Page**

- Changed layout of National Data Sheet to TI format ... 11

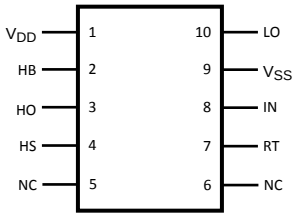
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5 Pin Configuration and Functions

D Package
8-Pin SOIC
Top View



DPR Package
10-Pin WSON
Top View



Pin Functions

PIN		NAME	DESCRIPTION	APPLICATION INFORMATION
SOIC	WSON			
1	1	V_{DD}	Positive gate drive supply	Locally decouple to V_{SS} using ESR/ESL capacitor, located as close to IC as possible.
2	2	HB	High-side gate driver bootstrap rail	Connect the positive terminal to bootstrap capacitor to the HB pin and connect negative terminal to HS. The Bootstrap capacitor should be placed as close to IC as possible
3	3	HO	High-side gate driver output	Connect to gate of high-side MOSFET with short low inductance path.
4	4	HS	High-side MOSFET source connection	Connect to bootstrap capacitor negative terminal and source of high-side MOSFET.
5	7	RT	Deadtime programming pin	Resistor from RT to ground programs the deadtime between high- and low-side transitions. The resistor should be located close to the IC to minimize noise coupling from adjacent traces.
6	8	IN	Control input	Logic 1 equals High-side ON and Low-side OFF. Logic 0 equals High-side OFF and Low-side ON.
7	9	V_{SS}	Ground return	All signals are referenced to this ground.
8	10	LO	Low-side gate driver output	Connect to the gate of the low-side MOSFET with a short low inductance path.

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6 Specifications

6.1 Absolute Maximum Ratings (1)(2)

	MIN	MAX	UNIT
V_{DD} to V_{SS}	–0.3	18	V
V_{HB} to V_{HS}	–0.3	18	V
IN to V_{SS}	–0.3	V_{DD} + 0.3	V
LO Output	–0.3	V_{DD} + 0.3	V
HO Output	V_{HS} – 0.3	V_{HB} + 0.3	V
V_{HS} to V_{SS}	−1	100	V
V_{HB} to V_{SS}		118	V
RT to V_{SS}	–0.3	5	V
Junction Temperature		150	°C
Storage temperature range, T_{stg}	–55	150	°C

(1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. *Recommended Operating Conditions* under which operation of the device is specified. Recommended Operating Conditions do not imply performance limits. For performance limits and associated test conditions, see *Electrical Characteristics*.
(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

	MIN	MAX	UNIT
V_{DD}	9	14	V
HS	–1	100	V
HB	V_{HS} + 8	V_{HS} + 14	V
HS Slew Rate		< 50	V/ns
Junction Temperature	–40	125	°C

6.4 Thermal Information

THERMAL METRIC (1)		LM5104		UNIT
		D	DPR	
		8 PINS	10 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	114.5	37.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	61.1	38.1	
$R_{\theta JB}$	Junction-to-board thermal resistance	55.6	14.9	
ψ_{JT}	Junction-to-top characterization parameter	9.7	0.4	
ψ_{JB}	Junction-to-board characterization parameter	54.9	15.2	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	4.4	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

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6.5 Electrical Characteristics

MIN and MAX limits apply over the full operating junction temperature range. Unless otherwise specified, T_J = +25°C, V_{DD} = V_{HB} = 12 V, V_{SS} = V_{HS} = 0 V, RT = 100kΩ. No Load on LO or HO.

	PARAMETER	TEST CONDITIONS	MIN(1)	TYP	MAX(1)	UNIT
SUPPLY CURRENTS						
I_{DD}	V_{DD} Quiescent Current	LI = HI = 0 V		0.4	0.6	mA
I_{DDO}	V_{DD} Operating Current	f = 500 kHz		1.9	3	mA
I_{HB}	Total HB Quiescent Current	LI = HI = 0 V		0.06	0.2	mA
I_{HBO}	Total HB Operating Current	f = 500 kHz		1.3	3	mA
I_{HBS}	HB to V_{SS} Current, Quiescent	V_{HS} = V_{HB} = 100 V		0.05	10	µA
I_{HBSO}	HB to V_{SS} Current, Operating	f = 500 kHz		0.08		mA
INPUT PINS						
V_{IL}	Low Level Input Voltage Threshold		0.8	1.8		V
V_{IH}	High Level Input Voltage Threshold			1.8	2.2	V
R_I	Input Pulldown Resistance		100	200	500	kΩ
TIME DELAY CONTROLS						
V_{RT}	Nominal Voltage at RT		2.7	3	3.3	V
I_{RT}	RT Pin Current Limit	RT = 0 V	0.75	1.5	2.25	mA
T_{D1}	Delay Timer, RT = 10 kΩ		58	90	130	ns
T_{D2}	Delay Timer, RT = 100 kΩ		140	200	270	ns
UNDER VOLTAGE PROTECTION						
V_{DDR}	V_{DD} Rising Threshold		6.0	6.9	7.4	V
V_{DDH}	V_{DD} Threshold Hysteresis			0.5		V
V_{HBR}	HB Rising Threshold		5.7	6.6	7.1	V
V_{HBH}	HB Threshold Hysteresis			0.4		V
BOOT STRAP DIODE						
V_{DL}	Low-Current Forward Voltage	I_{VDD-HB} = 100 µA		0.60	0.9	V
V_{DH}	High-Current Forward Voltage	I_{VDD-HB} = 100 mA		0.85	1.1	V
R_D	Dynamic Resistance	I_{VDD-HB} = 100 mA		0.8	1.5	Ω
LO GATE DRIVER						
V_{OLL}	Low-Level Output Voltage	I_{LO} = 100 mA		0.25	0.4	V
V_{OHL}	High-Level Output Voltage	I_{LO} = –100 mA V_{OHL} = V_{DD} – V_{LO}		0.35	0.55	V
I_{OHL}	Peak Pullup Current	V_{LO} = 0 V		1.6		A
I_{OLL}	Peak Pulldown Current	V_{LO} = 12 V		1.8		A
HO GATE DRIVER						
V_{OLH}	Low-Level Output Voltage	I_{HO} = 100 mA		0.25	0.4	V
V_{OHH}	High-Level Output Voltage	I_{HO} = –100 mA, V_{OHH} = V_{HB} – V_{HO}		0.35	0.55	V
I_{OHH}	Peak Pullup Current	V_{HO} = 0 V		1.6		A
I_{OLH}	Peak Pulldown Current	V_{HO} = 12 V		1.8		A

(1) Min and Max limits are 100% production tested at 25°C. Limits over the operating temperature range are specified through correlation using Statistical Quality Control (SQC) methods. Limits are used to calculate Average Outgoing Quality Level (AOQL).

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6.6 Switching Characteristics

MAX limits apply over the full operating junction temperature range. Unless otherwise specified, T_J = +25°C, V_{DD} = V_{HB} = 12 V, V_{SS} = V_{HS} = 0 V, No Load on LO or HO .

	PARAMETER	TEST CONDITIONS	MIN(1)	TYP	MAX(1)	UNIT
t_{LPHL}	Lower Turn-Off Propagation Delay (IN Rising to LO Falling)			25	56	ns
t_{HPHL}	Upper Turn-Off Propagation Delay (IN Falling to HO Falling)			25	56	
t_{RC}, t_{FC}	Either Output Rise/Fall Time	C_L = 1000 pF		15		
t_R, t_F	Either Output Rise/Fall Time (3V to 9V)	C_L = 0.1 µF		0.6		µs
t_{BS}	Bootstrap Diode Turn-Off Time	I_F = 20 mA, I_R = 200 mA		50		ns

(1) Min and Max limits are 100% production tested at 25°C. Limits over the operating temperature range are specified through correlation using Statistical Quality Control (SQC) methods. Limits are used to calculate Average Outgoing Quality Level (AOQL).

6.7 Typical Characteristics

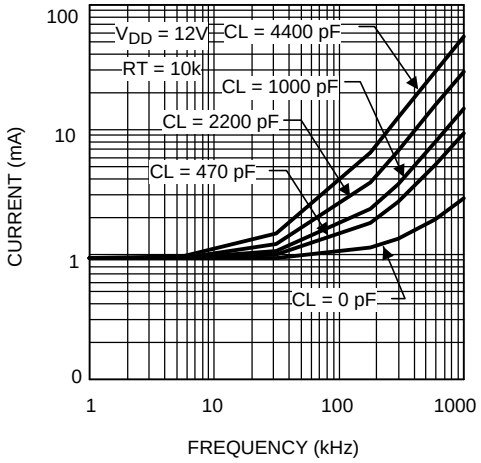


Figure 1. I_{DD} vs Frequency

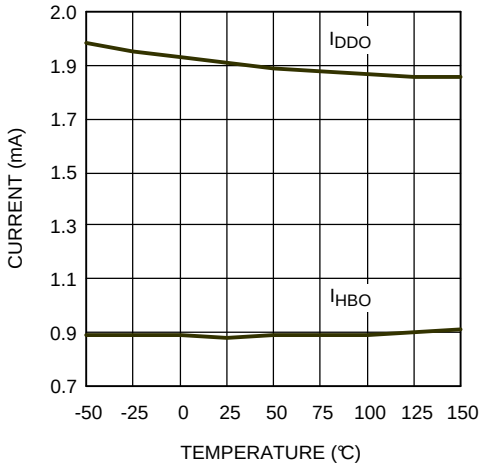


Figure 2. Operating Current vs Temperature

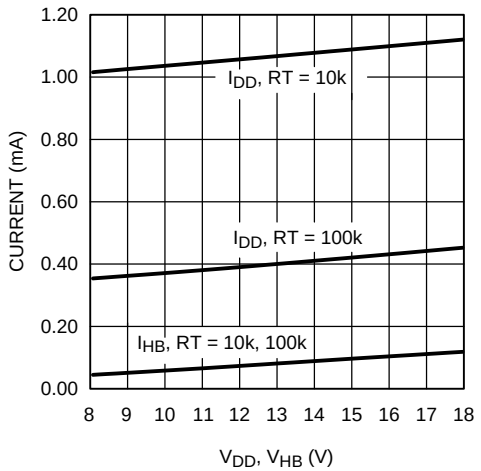


Figure 3. Quiescent Current vs Supply Voltage

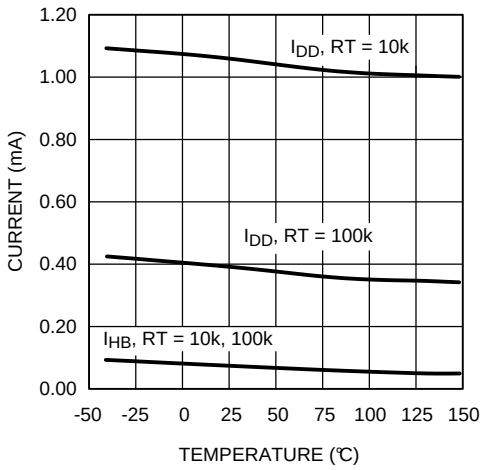


Figure 4. Quiescent Current vs Temperature

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Typical Characteristics (continued)

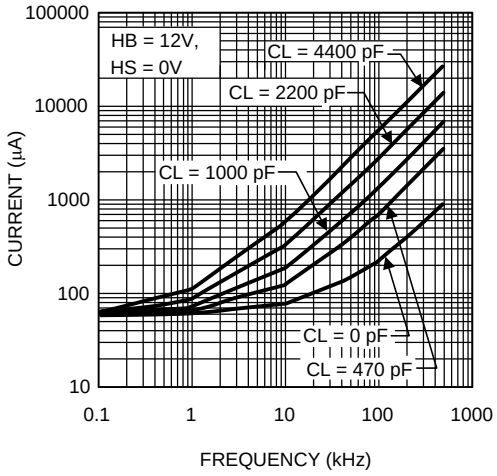


Figure 5. I_{HB} vs Frequency

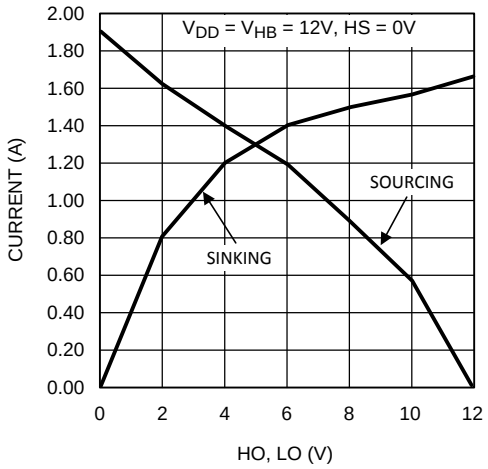


Figure 6. HO & LO Peak Output Current vs Output Voltage

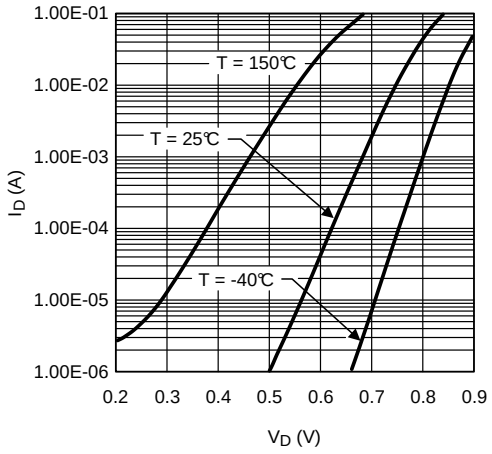


Figure 7. Diode Forward Voltage

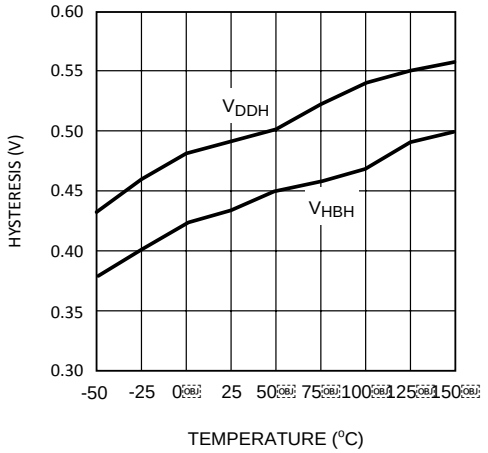


Figure 8. Undervoltage Threshold Hysteresis vs Temperature

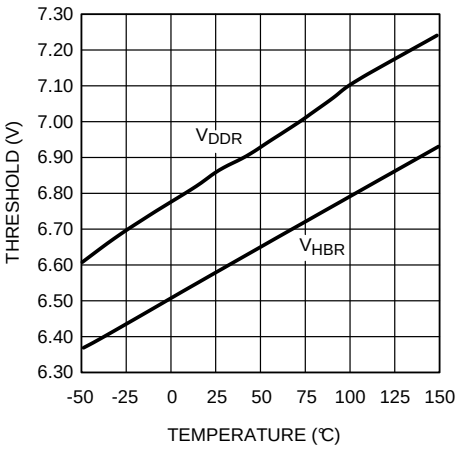


Figure 9. Undervoltage Rising Threshold vs Temperature

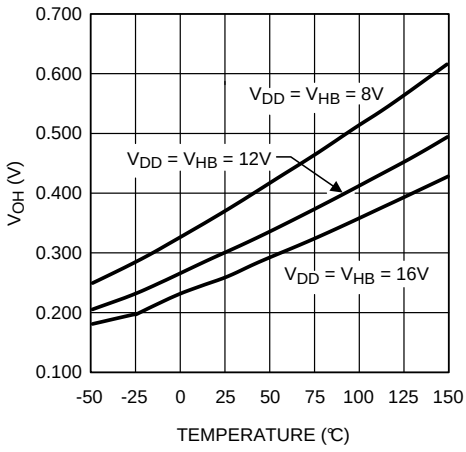


Figure 10. LO and HO Gate Drive—High-Level Output Voltage vs Temperature

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Typical Characteristics (continued)

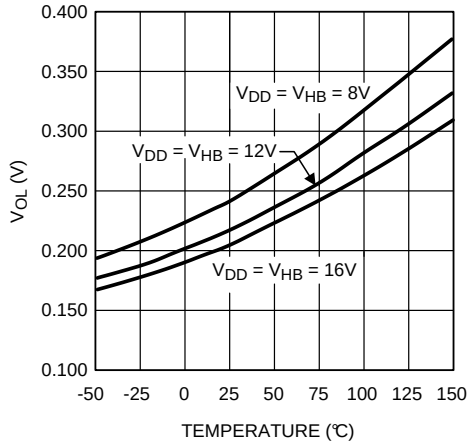


Figure 11. LO and HO Gate Drive—Low-Level Output Voltage vs Temperature

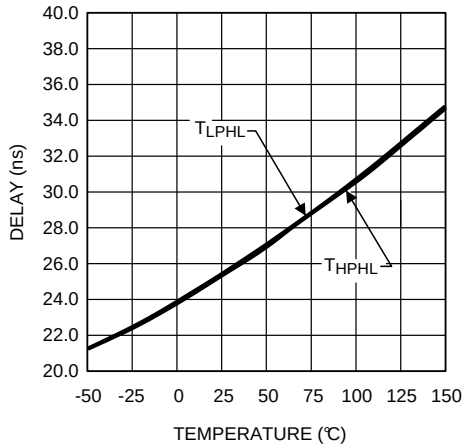


Figure 12. Turn Off Propagation Delay vs Temperature

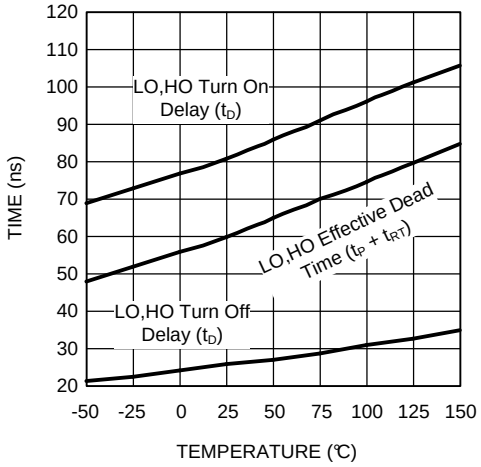


Figure 13. Timing vs Temperature RT = 10K

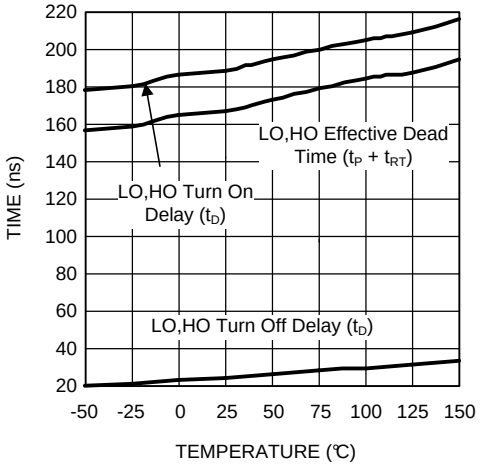


Figure 14. Timing vs Temperature RT = 100K

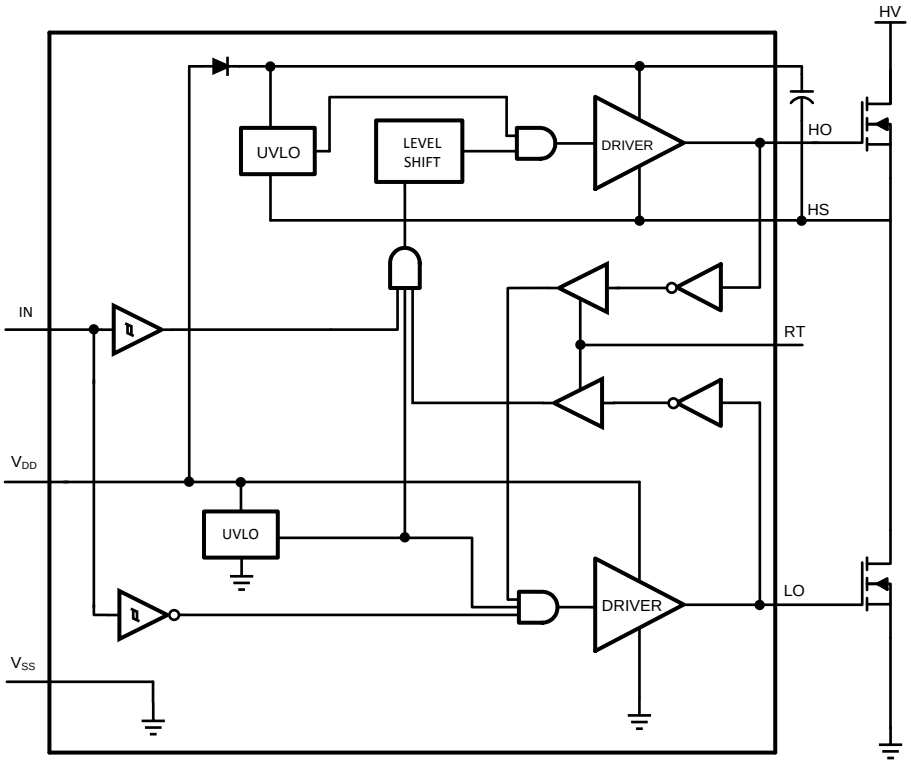
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7 Detailed Description

7.1 Overview

The LM5104 High Voltage gate driver is designed to drive both the high side and the low side N-Channel MOSFETs in a synchronous buck configuration. The floating high-side driver is capable of working with supply voltages up to 100 V. The high side and low side gate drivers are controlled from a single input. Each change in state is controlled in an adaptive manner to prevent shoot-through issues. In addition to the adaptive transition timing, an additional delay time can be added, proportional to an external setting resistor. An integrated high voltage diode is provided to charge high side gate drive bootstrap capacitor. A robust level shifter operates at high speed while consuming low power and providing clean level transitions from the control logic to the high side gate driver. Under-voltage lockout is provided on both the low side and the high side power rails.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Adaptive Shoot-Through Protection

LM5104 is a high voltage, high speed dual output driver designed to drive top and bottom MOSFET's connected in synchronous buck or half-bridge configuration, from one externally provided PWM signal. LM5104 features adaptive delay to prevent shoot-through current through top and bottom MOSFETs during switching transitions. Referring to the timing diagram Figure 16, the rising edge of the PWM input (IN) turns off the bottom MOSFET (LO) after a short propagation delay (t_P). An adaptive circuit in the LM5104 monitors the bottom gate voltage (LO) and triggers a programmable delay generator when the LO pin falls below an internally set threshold (≈ $V_{dd}/2$). The gate drive of the upper MOSFET (HO) is disabled until the deadtime expires. The upper gate is enabled after the TIMER delay (t_P+T_{RT}), and the upper MOSFET turns-on. The additional delay of the timer prevents lower and upper MOSFETs from conducting simultaneously, thereby preventing shoot-through.

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Feature Description (continued)

A falling transition on the PWM signal (IN) initiates the turn-off of the upper MOSFET and turn-on of the lower MOSFET. A short propagation delay (t_P) is encountered before the upper gate voltage begins to fall. Again, the adaptive shoot-through circuitry and the programmable deadtime TIMER delays the lower gate turn-on time. The upper MOSFET gate voltage is monitored and the deadtime delay generator is triggered when the upper MOSFET gate voltage with respect to ground drops below an internally set threshold (≈ V_{dd}/2). The lower gate drive is momentarily disabled by the timer and turns on the lower MOSFET after the deadtime delay expires (t_P+T_{RT}).

The RT pin is biased at 3V and current limited to 1mA. It is designed to accommodate a resistor between 5K and 100K, resulting in an effective dead-time proportional to RT and ranging from 90ns to 200ns. RT values below 5K will saturate the timer and are not recommended.

7.3.2 Start-up and UVLO

Both top and bottom drivers include undervoltage lockout (UVLO) protection circuitry which monitors the supply voltage (V_{DD}) and bootstrap capacitor voltage (V_{HB} – V_{HS}) independently. The UVLO circuit inhibits each driver until sufficient supply voltage is available to turn-on the external MOSFETs, and the built-in hysteresis prevents chattering during supply voltage transitions. When the supply voltage is applied to V_{DD} pin of LM5104, the top and bottom gates are held low until V_{DD} exceeds UVLO threshold, typically about 6.9 V. Any UVLO condition on the bootstrap capacitor will disable only the high-side output (HO).

7.4 Device Functional Modes

IN Pin	LO Pin	HO Pin
L	H	L
H	L	H

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8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM5104 is one of the latest generation of high-voltage gate drivers which are designed to drive both the high-side and low-side N-channel MOSFETs in a half-bridge/full bridge configuration or in a synchronous buck circuit. The floating high-side driver can operate with supply voltages up to 100 V. This allows for N-channel MOSFET control in half-bridge, full-bridge, push-pull, two switch forward and active clamp topologies.

Table 1. Highlights

FEATURE	BENEFIT
Adaptive Rising and Falling Edges with Programmable Additional Delay	Allows optimization of gate drive timings to account for device differences between high-side and low-side positions.
Single Input Control	Direct drive from lower cost PWM controllers
Internal Bootstrap Diode	Reduces parts count and PCB real estate

8.2 Typical Application

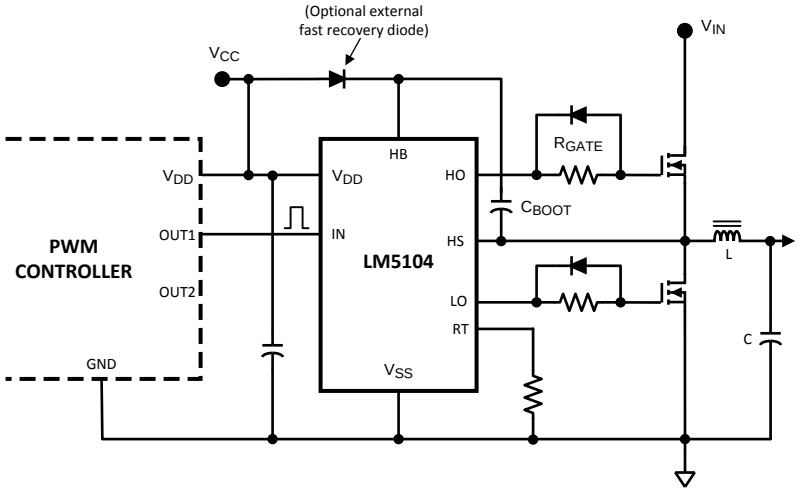


Figure 15. LM5104 Driving MOSFETs Connected in Synchronous Buck Configuration

Typical Application (continued)

8.2.1 Design Requirements

PARAMETER	VALUE
Gate Driver IC	LM5104
Mosfet	CSD18531Q5A
V_{DD}	10 V
Q_{gmax}	43 nC
F_{sw}	200 kHz
D_{Max}	95%
I_{HBO}	10 µA
V_{DH}	1.1 V
V_{HBR}	7.1 V
V_{HBH}	0.4 V

8.2.2 Detailed Design Procedure

$\Delta V_{HB} = V_{DD} - V_{DH} - V_{HBL}$

where

- V_{DD} = Supply voltage of the gate drive IC
- V_{DH} = Bootstrap diode forward voltage drop
- V_{gsmin} = Minimum gate source threshold voltage (1)

$$C_{BOOT} = \frac{Q_{TOTAL}}{\Delta V_{HB}} \quad (2)$$

$$Q_{TOTAL} = Q_{gmax} + I_{HBO} \times \frac{D_{Max}}{F_{SW}} \quad (3)$$

The quiescent current of the bootstrap circuit is 10 µA which is negligible compared to the Qgs of the MOSFET.

$$Q_{TOTAL} = 43nC + 10\mu A \times \frac{0.95}{100kHz} \quad (4)$$

Q_{TOTAL} = 43.01 nC (5)

In practice the value for the C_{BOOT} capacitor should be greater than that calculated to allow for situations where the power stage may skip pulse due to load transients. In this circumstance the boot capacitor must maintain the HB pin voltage above the UVLO voltage for the HB circuit.

As a general rule the local V_{DD} bypass capacitor should be 10 times greater than the value of C_{BOOT}.

$V_{HBL} = V_{HBR} - V_{HBH}$ (6)

V_{HBL} = 6.7 V (7)

ΔV_{HB} = 10 V – 1.1 V – 6.7 V (8)

ΔV_{HB} = 2.2 V (9)

$$C_{BOOT} = \frac{43.01nc}{2.2V} \quad (10)$$

C_{BOOT} = 19.54 nF (11)

The bootstrap and bias capacitors should be ceramic types with X7R dielectric. The voltage rating should be twice that of the maximum V_{DD} to allow for loss of capacitance once the devices have a DC bias voltage across them and to ensure long-term reliability of the devices.

An additional delay turn-on delay can be programmed using an external resistor, RT. Figure 17 shows the relationship between the turnon delay time and the resistor value for RT.

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8.2.3 Application Curves

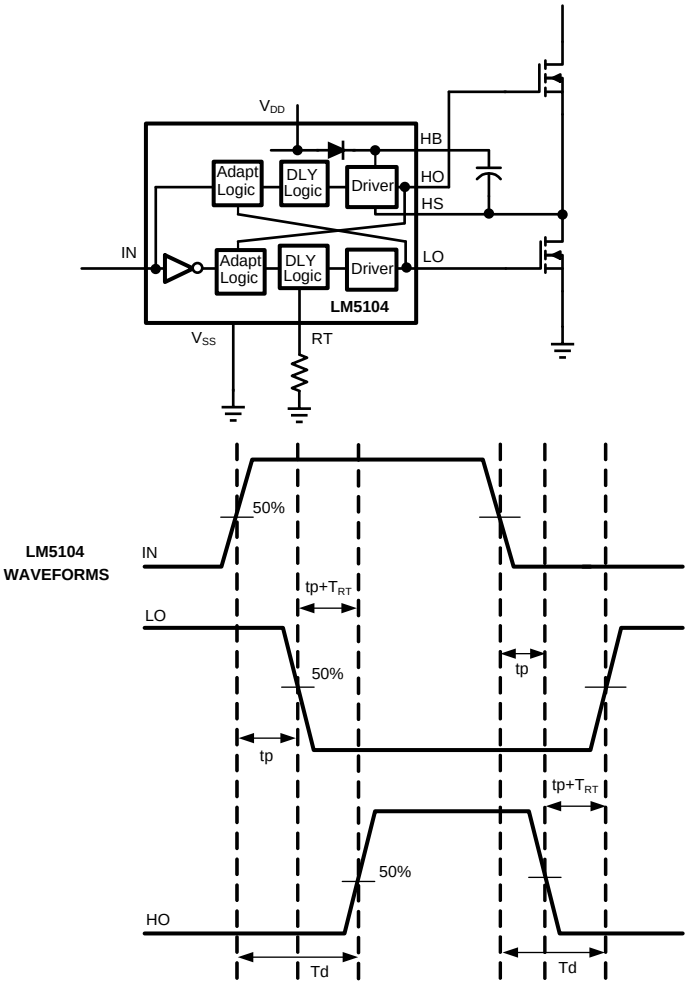


Figure 16. Application Timing Waveforms

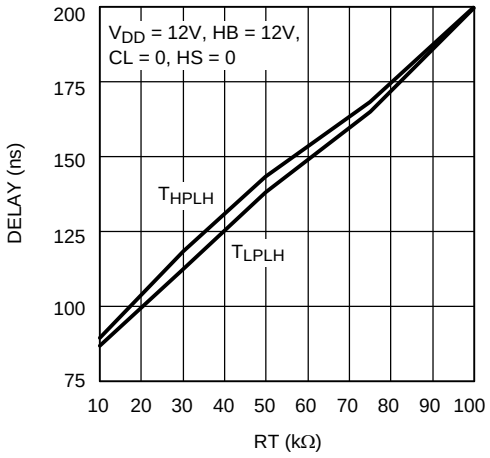


Figure 17. Turn On Delay vs RT Resistor Value

9 Power Supply Recommendations

9.1 Power Dissipation Considerations

The total IC power dissipation is the sum of the gate driver losses and the bootstrap diode losses. The gate driver losses are related to the switching frequency (f), output load capacitance on LO and HO (C_L), and supply voltage (V_{DD}) and can be roughly calculated as:

$$P_{DGATES} = 2 \bullet f \bullet C_L \bullet V_{DD}^2 \quad (12)$$

There are some additional losses in the gate drivers due to the internal CMOS stages used to buffer the LO and HO outputs. The plot in Figure 18 shows the measured gate driver power dissipation versus frequency and load capacitance. At higher frequencies and load capacitance values, the power dissipation is dominated by the power losses driving the output loads and agrees well with Equation 12. This plot can be used to approximate the power losses due to the gate drivers.

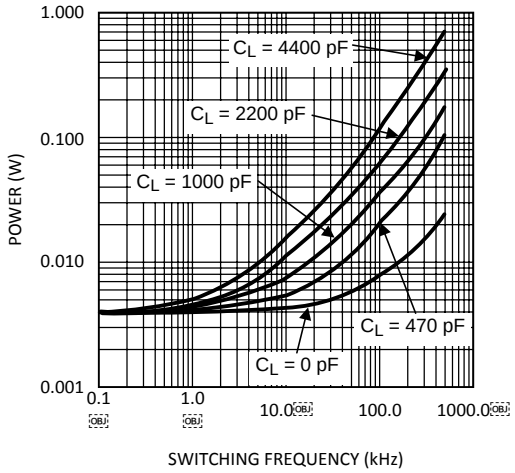


Figure 18. Gate Driver Power Dissipation (LO + HO)
V_{CC} = 12V, Neglecting Diode Losses

The bootstrap diode power loss is the sum of the forward bias power loss that occurs while charging the bootstrap capacitor and the reverse bias power loss that occurs during reverse recovery. Since each of these events happens once per cycle, the diode power loss is proportional to frequency. Larger capacitive loads require more current to recharge the bootstrap capacitor resulting in more losses. Higher input voltages (V_{IN}) to the half bridge result in higher reverse recovery losses. The following plot was generated based on calculations and lab measurements of the diode recovery time and current under several operating conditions. This can be useful for approximating the diode power dissipation.

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Power Dissipation Considerations (continued)

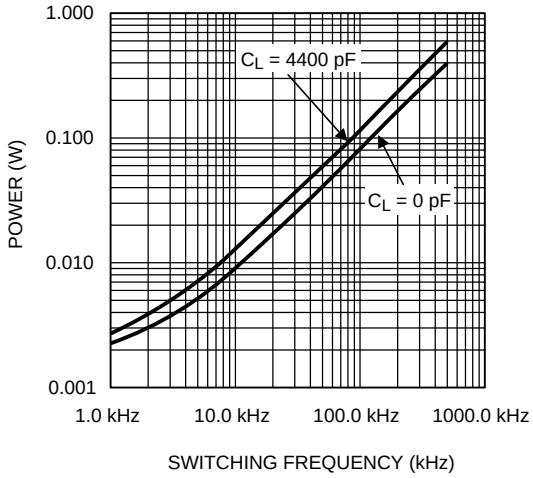


Figure 19. Diode Power Dissipation V_{IN} = 80V

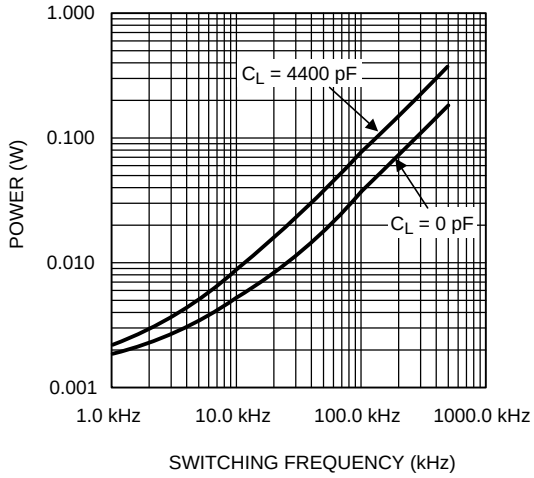


Figure 20. Diode Power Dissipation V_{IN} = 40V

The total IC power dissipation can be estimated from the above plots by summing the gate drive losses with the bootstrap diode losses for the intended application. Because the diode losses can be significant, an external diode placed in parallel with the internal bootstrap diode (refer to Figure 15) can be helpful in removing power from the IC. For this to be effective, the external diode must be placed close to the IC to minimize series inductance and have a significantly lower forward voltage drop than the internal diode.

10 Layout

10.1 Layout Guidelines

The optimum performance of high- and low-side gate drivers cannot be achieved without taking due considerations during circuit board layout. Following points are emphasized.

1. A low ESR/ESL capacitor must be connected close to the IC, and between V_{DD} and V_{SS} pins and between HB and HS pins to support high peak currents being drawn from V_{DD} during turnon of the external MOSFET.
2. To prevent large voltage transients at the drain of the top MOSFET, a low ESR electrolytic capacitor must be connected between MOSFET drain and ground (V_{SS}).
3. To avoid large negative transients on the switch node (HS) pin, the parasitic inductances in the source of top MOSFET and in the drain of the bottom MOSFET (synchronous rectifier) must be minimized.
4. Grounding considerations:
   - a) The first priority in designing grounding connections is to confine the high peak currents from charging and discharging the MOSFET gate in a minimal physical area. This will decrease the loop inductance and minimize noise issues on the gate terminal of the MOSFET. The MOSFETs should be placed as close as possible to the gate driver.
   - b) The second high current path includes the bootstrap capacitor, the bootstrap diode, the local ground referenced bypass capacitor and low-side MOSFET body diode. The bootstrap capacitor is recharged on the cycle-by-cycle basis through the bootstrap diode from the ground referenced V_{DD} bypass capacitor. The recharging occurs in a short time interval and involves high peak current. Minimizing this loop length and area on the circuit board is important to ensure reliable operation.
5. The resistor on the RT pin must be placed very close to the IC and seperated from high current paths to avoid noise coupling to the time delay generator which could disrupt timer operation.

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10.2 Layout Example

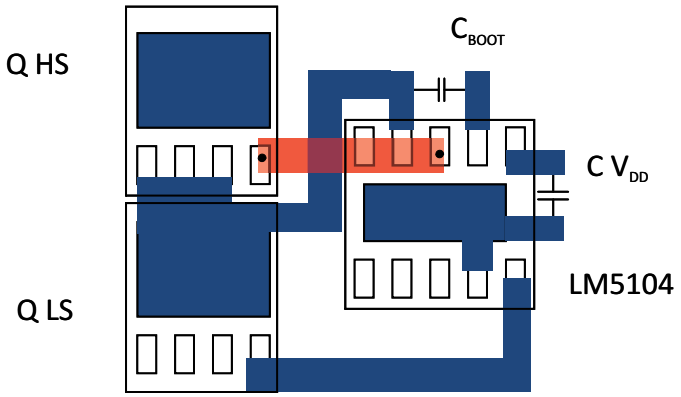


Figure 21. LM5104 Component Placement

11 Device and Documentation Support

11.1 Trademarks

All trademarks are the property of their respective owners.

11.2 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.3 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM5104M	NRND	SOIC	D	8	95	Non-RoHS & Green	Call TI	Level-1-235C-UNLIM	-40 to 125	5104 M	
LM5104M/NOPB	ACTIVE	SOIC	D	8	95	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	5104 M	Samples
LM5104MX/NOPB	ACTIVE	SOIC	D	8	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	5104 M	Samples
LM5104SD/NOPB	ACTIVE	WSON	DPR	10	1000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	5104SD	Samples
LM5104SDX/NOPB	ACTIVE	WSON	DPR	10	4500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	5104SD	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

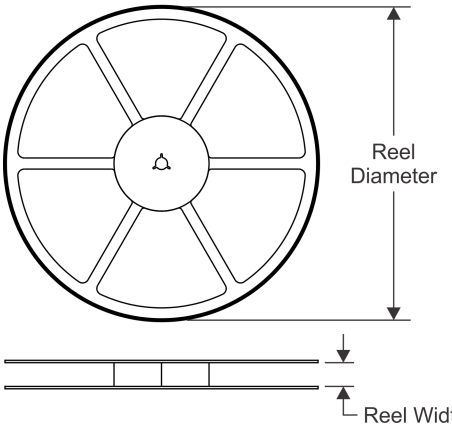
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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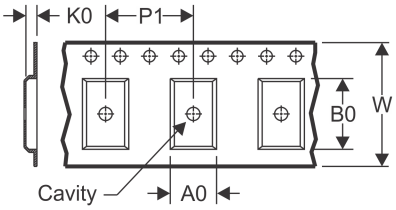
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

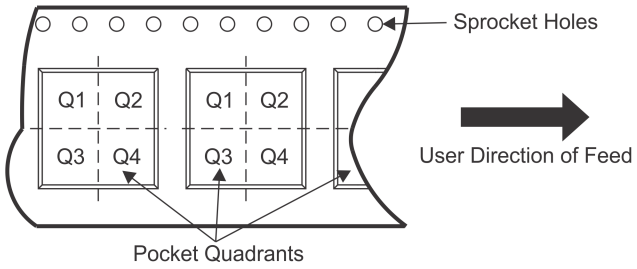


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

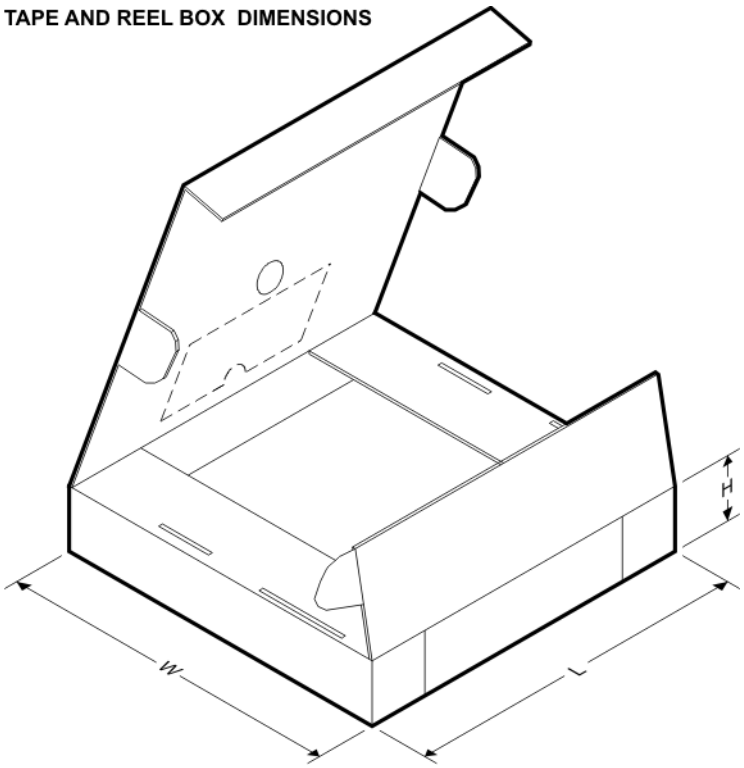
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM5104MX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM5104SD/NOPB	WSON	DPR	10	1000	178.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1
LM5104SDX/NOPB	WSON	DPR	10	4500	330.0	12.4	4.3	4.3	1.3	8.0	12.0	Q1

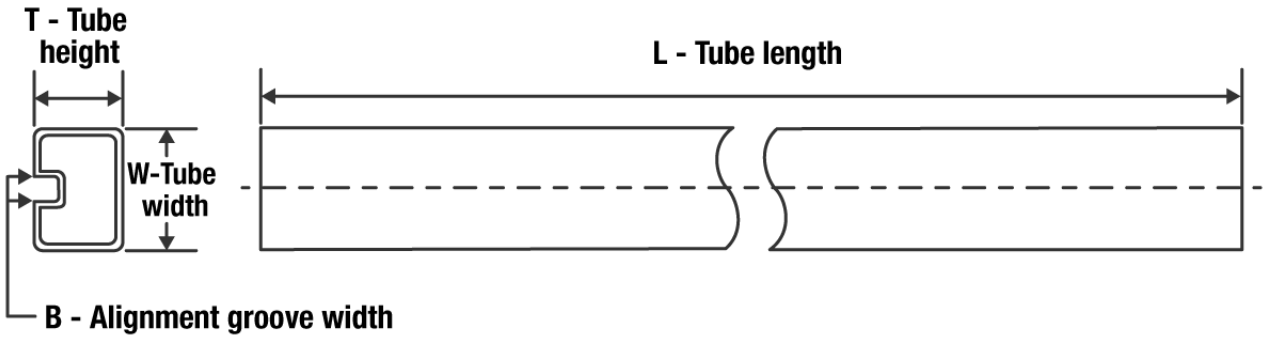
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM5104MX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM5104SD/NOPB	WSON	DPR	10	1000	208.0	191.0	35.0
LM5104SDX/NOPB	WSON	DPR	10	4500	367.0	367.0	35.0

TUBE



*All dimensions are nominal

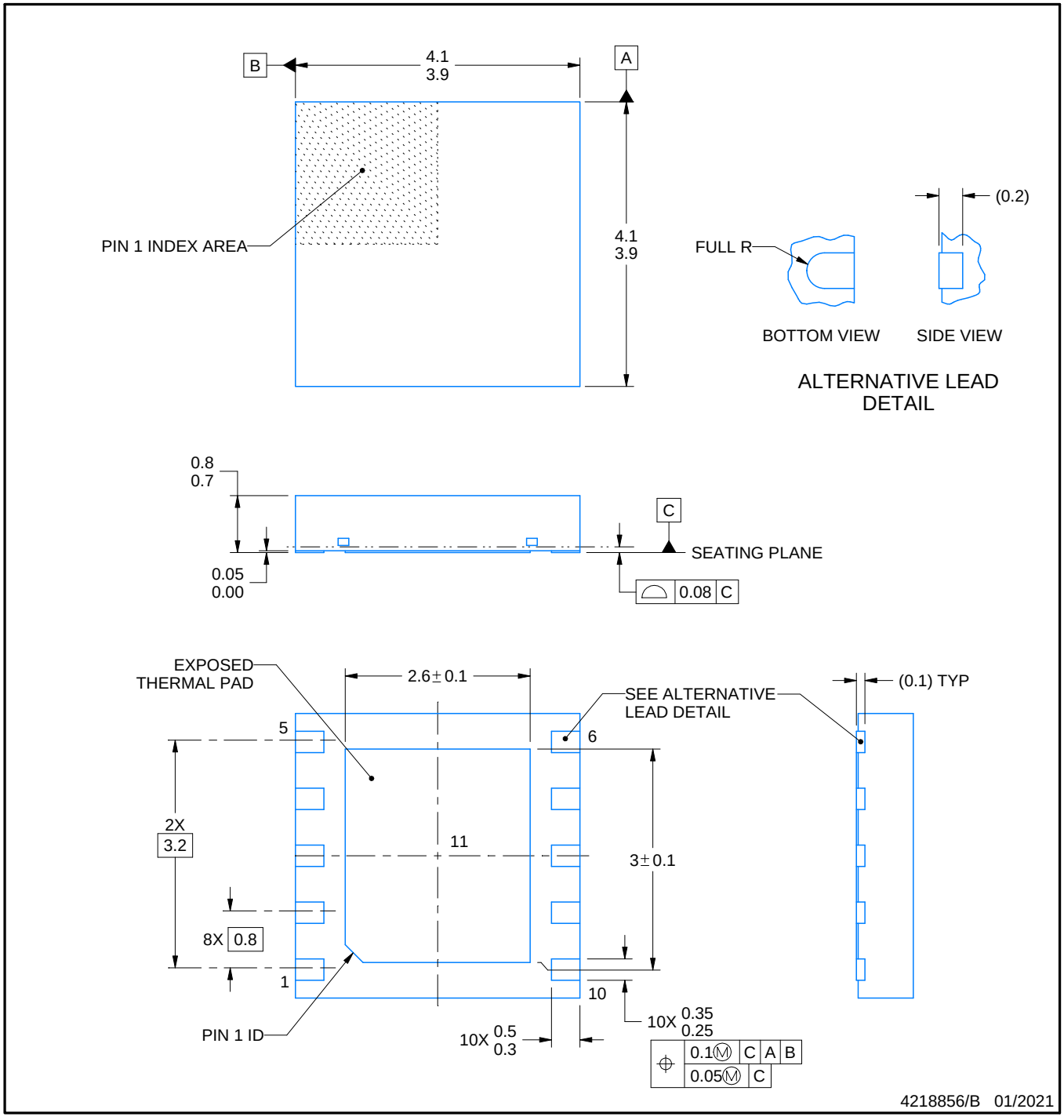
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LM5104M	D	SOIC	8	95	495	8	4064	3.05
LM5104M	D	SOIC	8	95	495	8	4064	3.05
LM5104M/NOPB	D	SOIC	8	95	495	8	4064	3.05

PACKAGE OUTLINE

DPR0010A

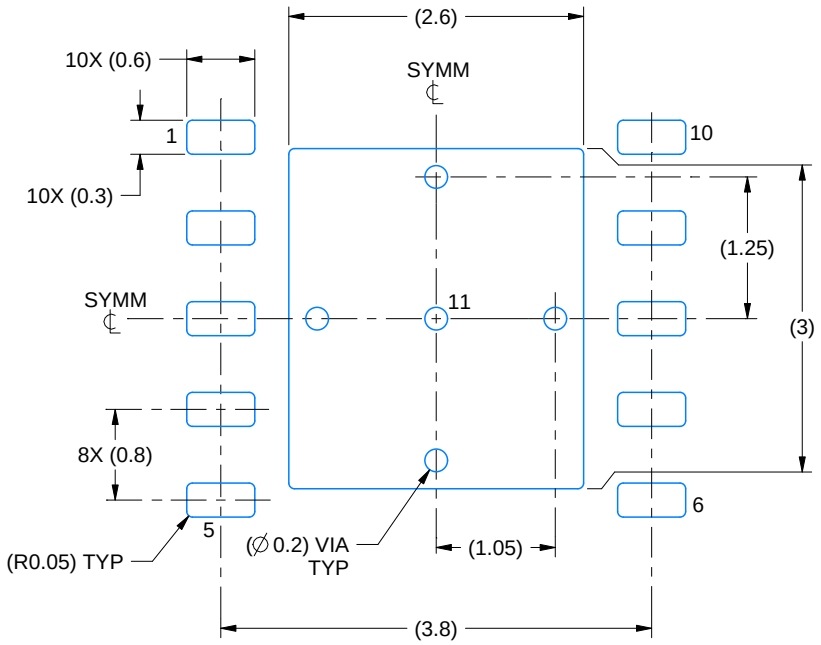
WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

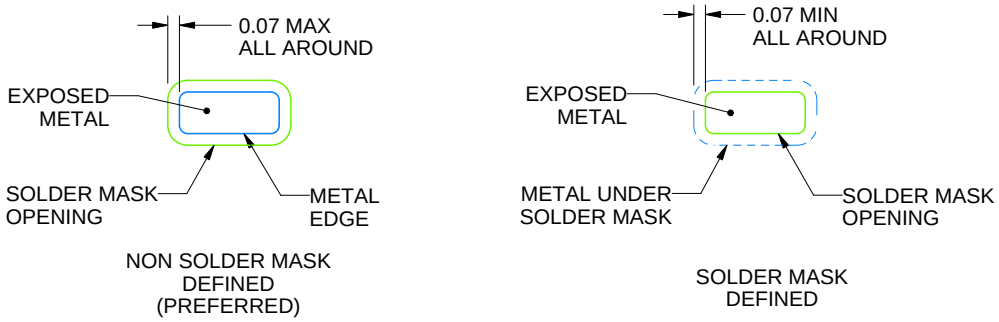


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

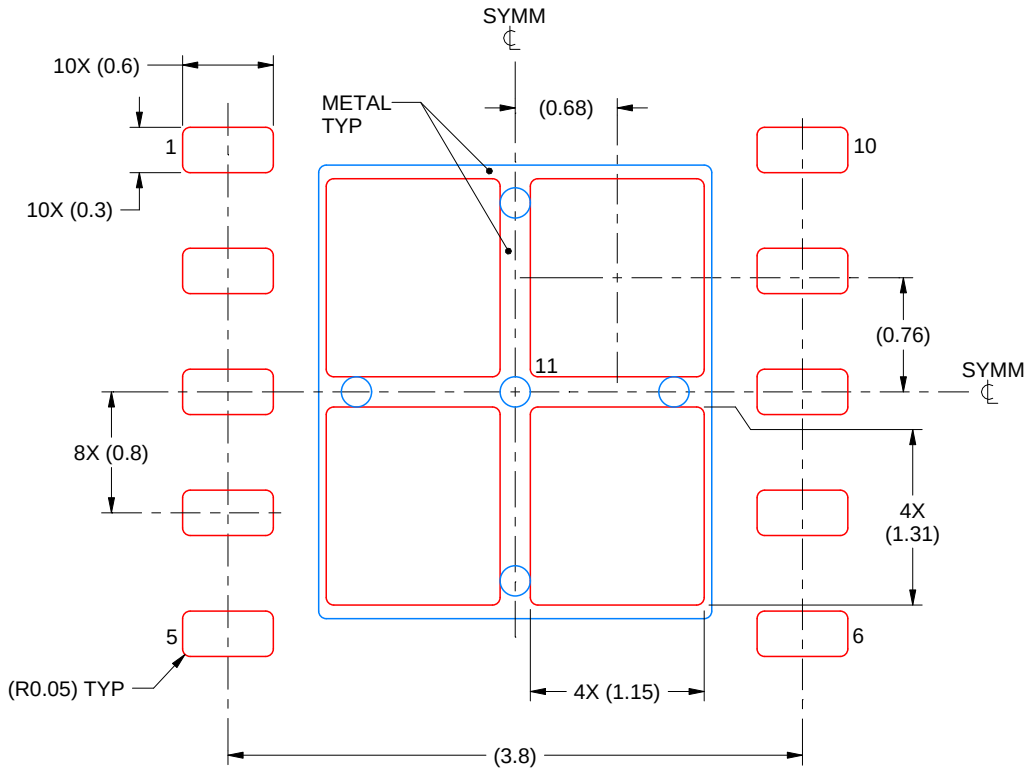


SOLDER MASK DETAILS

4218856/B 01/2021

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



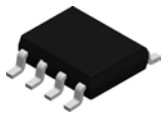
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 11:
77% PRINTED SOLDER COVERAGE BY AREA
SCALE:20X

4218856/B 01/2021

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

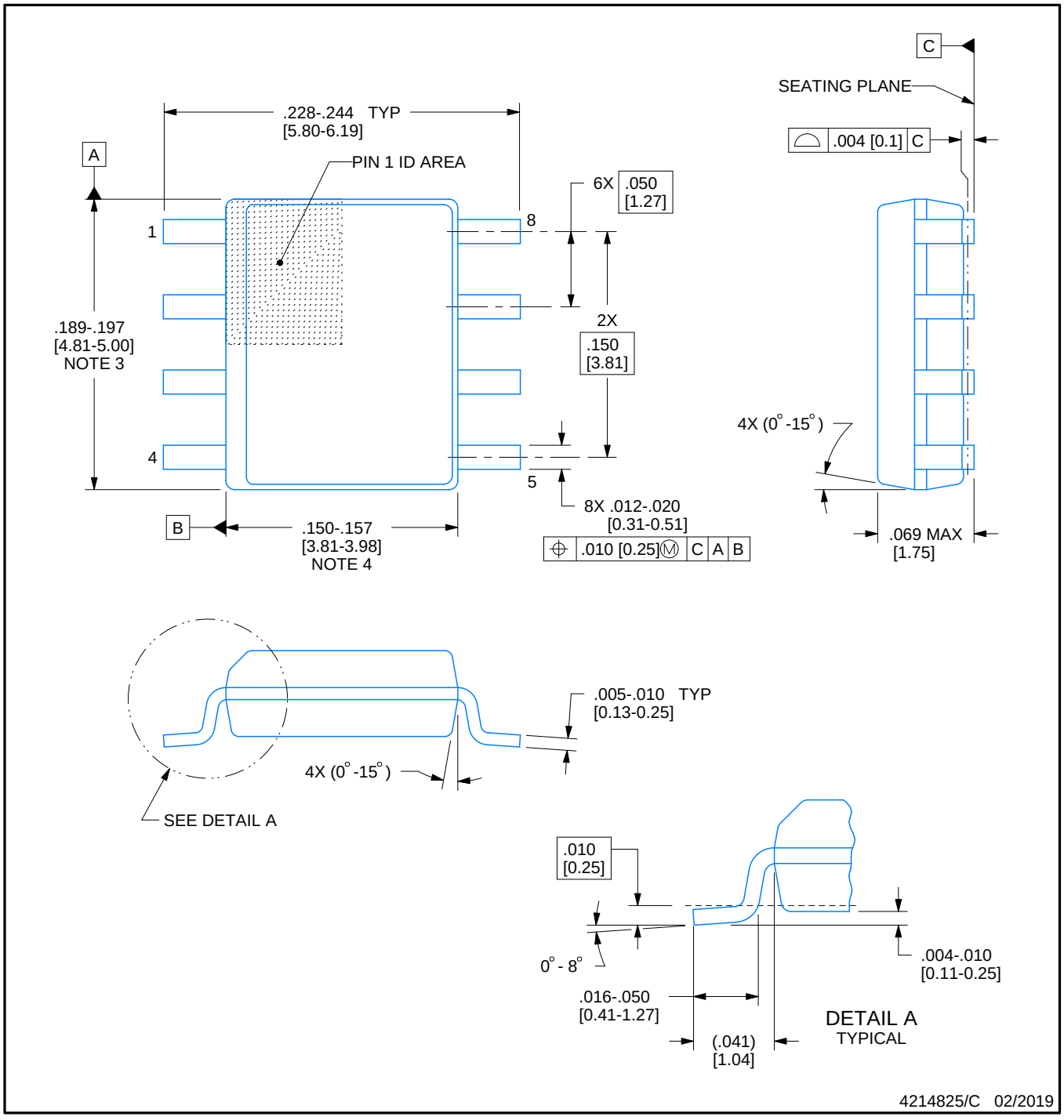


PACKAGE OUTLINE

D0008A

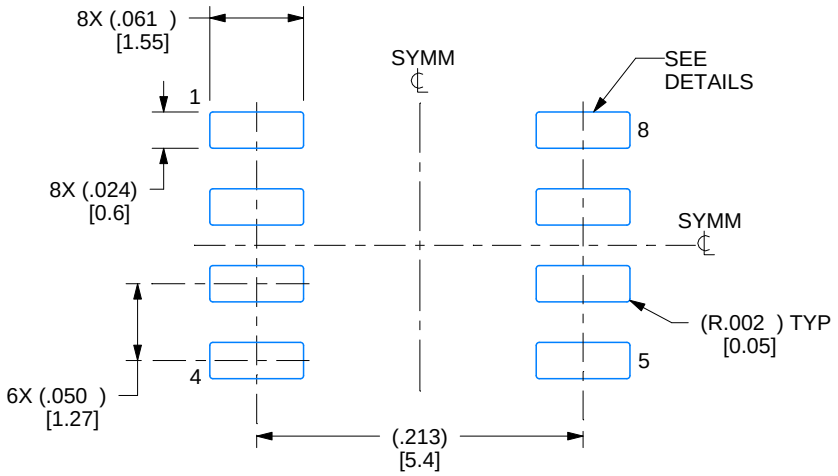
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

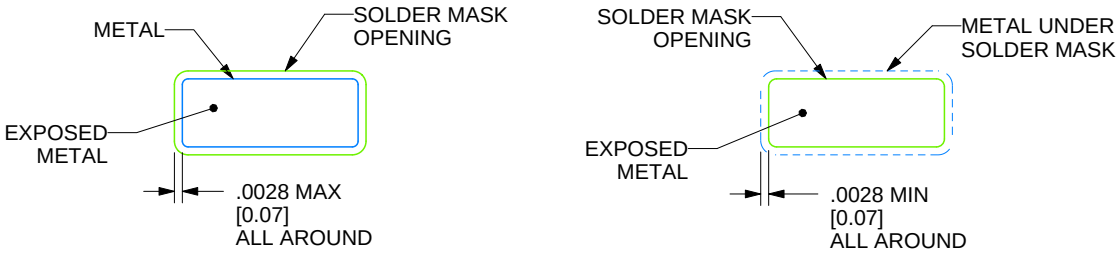


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

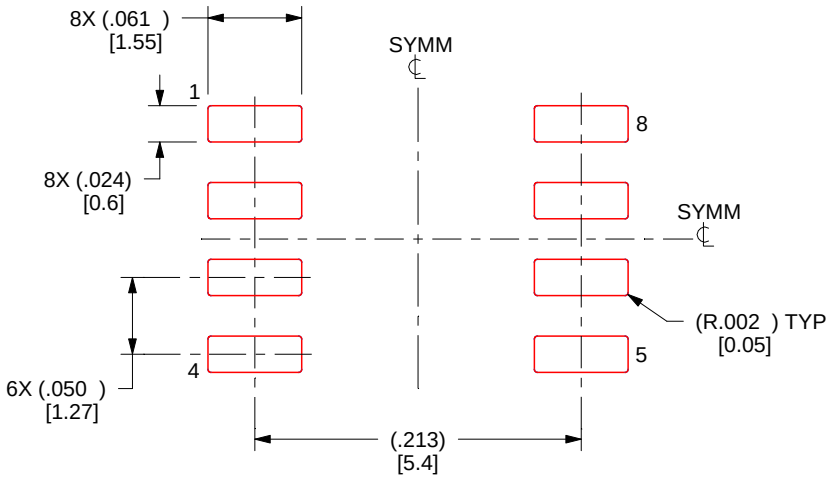
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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